

Product Specification

XBLW AOD4185

P-Channel Enhancement Mode MOSFET

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Description

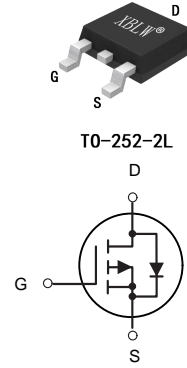
The AOD4185 uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

- VDS = -40V ID = -40A
- RDS(ON) < 19 mΩ @VGS=10V

Application

- Battery protection
- Load switch
- Uninterruptible power supply



P-Channel MOSFET

Package Marking and Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
XBLW AOD4185	TO-252-2L	AOD4185	Tape	2500Pcs/Reel

Absolute Maximum Ratings (TC=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	-40	V
VGS	Gate-Source Voltage	± 20	V
ID@Tc=25°C	Continuous Drain Current, VGS @ 10V ¹	-40	A
ID@Tc=100°C	Continuous Drain Current, VGS @ 10V ¹	-22	A
IDM	Pulsed Drain Current ²	-140	A
PD@Tc=25°C	Total Power Dissipation ⁴	40.3	W
TSTG	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
RθJA	Thermal Resistance Junction-ambient ¹	66	°C/W
RθJC	Thermal Resistance Junction-Case ¹	3.1	°C/W

Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Static Characteristics							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-40	-	-	V	
Gate-body Leakage current	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -40V, V _{GS} = 0V	T _J =25°C	-	-	-1	μA
			T _J =100°C	-	-	-100	
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1.0	-1.5	-2.2	V	
Drain-Source On-Resistance ⁴	R _{DS(on)}	V _{GS} = -10V, I _D = -20A	-	13.5	19	mΩ	
		V _{GS} = -4.5V, I _D = -15A	-	19.5	25		
Forward Transconductance ⁴	g _{fs}	V _{DS} = -10V, I _D = -20A	-	44	-	S	
Dynamic Characteristics⁵							
Input Capacitance	C _{iss}	V _{DS} = -20V, V _{GS} = 0V, f = 1MHz	-	2525	-	pF	
Output Capacitance	C _{oss}		-	190	-		
Reverse Transfer Capacitance	C _{rss}		-	172	-		
Gate Resistance	R _g	f = 1MHz	-	10	-	Ω	
Switching Characteristics⁵							
Total Gate Charge	Q _g	V _{GS} = -10V, V _{DS} = -20V, I _D = -20A	-	35	-	nC	
Gate-Source Charge	Q _{gs}		-	5.5	-		
Gate-Drain Charge	Q _{gd}		-	8	-		
Turn-On Delay Time	t _{d(on)}	V _{GS} = -10V, V _{DD} = -20V, R _G = 3Ω, I _D = -20A	-	14.5	-	ns	
Rise Time	t _r		-	20.2	-		
Turn-Off Delay Time	t _{d(off)}		-	32	-		
Fall Time	t _f		-	10	-		
Drain-Source Body Diode Characteristics							
Diode Forward Voltage ⁴	V _{SD}	I _S = -20A, V _{GS} = 0V	-	-	-1.2	V	
Continuous Source Current	I _S	T _C =25°C	-	-	-40	A	

Note :

1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.
2. The EAS data shows Max. rating . The test condition is V_{DD}= -25V, V_{GS}= -10V, L= 0.1mH, I_{AS}= -34A.
3. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics

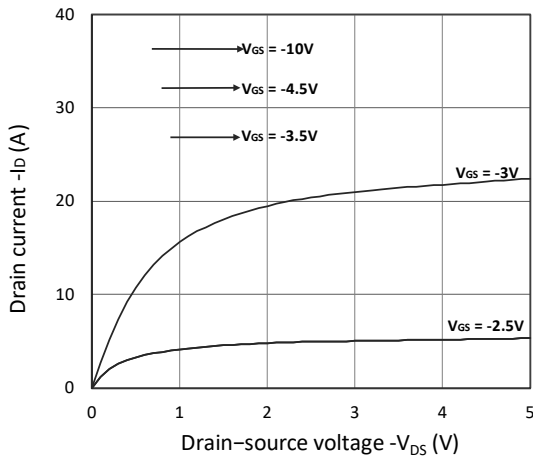


Figure 1. Output Characteristics

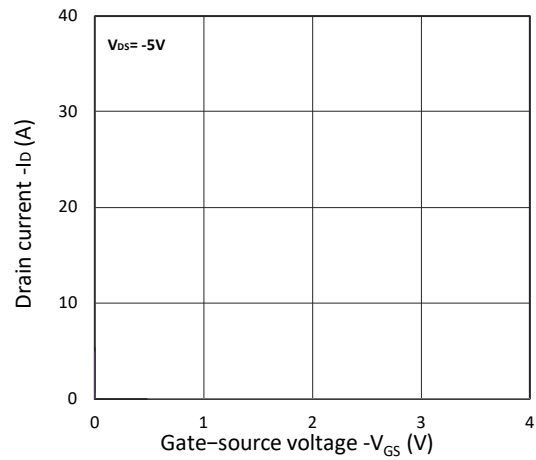


Figure 2. Transfer Characteristics

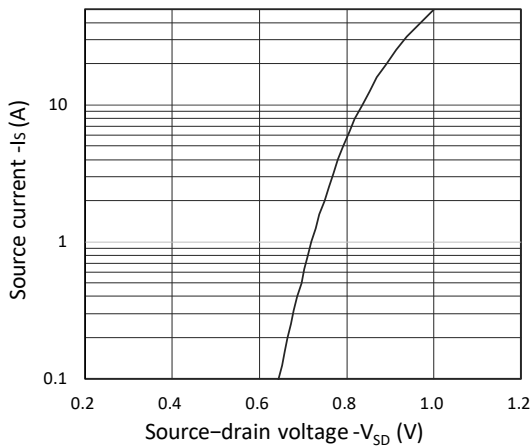


Figure 3. Forward Characteristics of Reverse

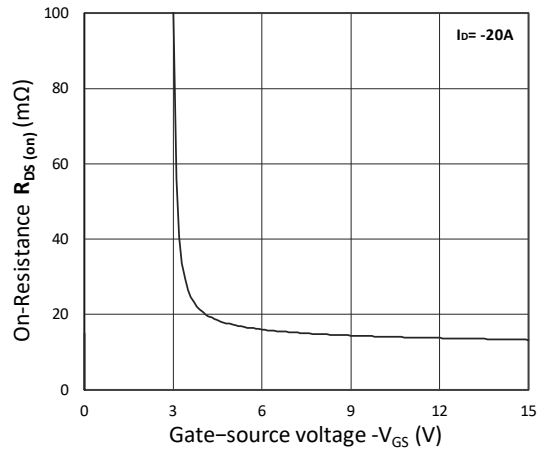


Figure 4. $R_{DS(on)}$ vs. V_{GS}

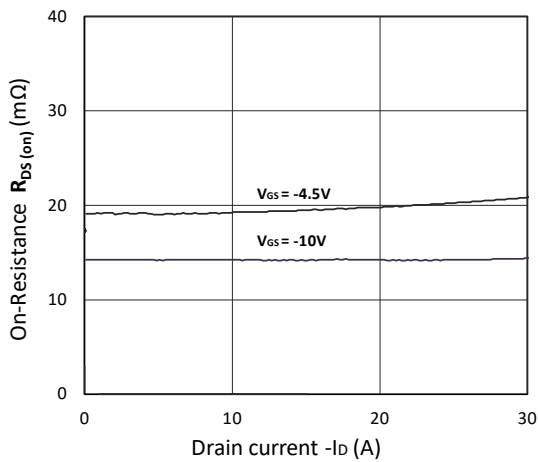


Figure 5. $R_{DS(on)}$ vs. I_D

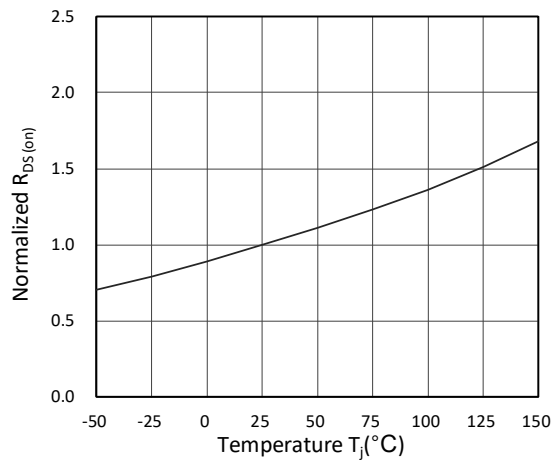


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

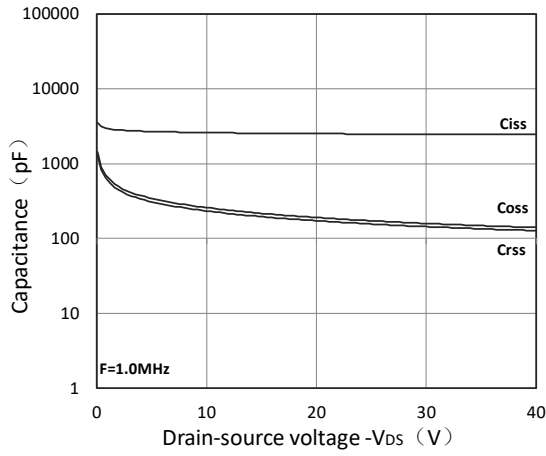


Figure 7. Capacitance Characteristics

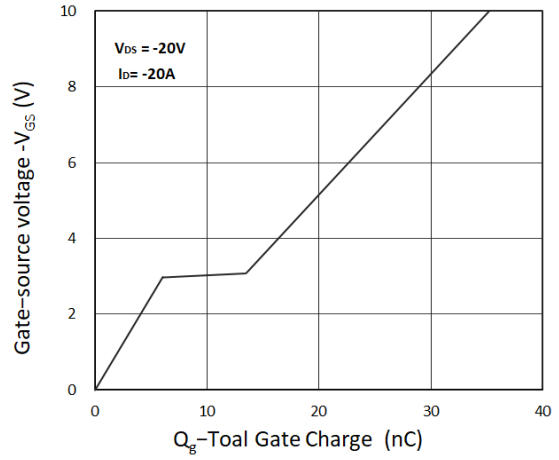


Figure 8. Gate Charge Characteristics

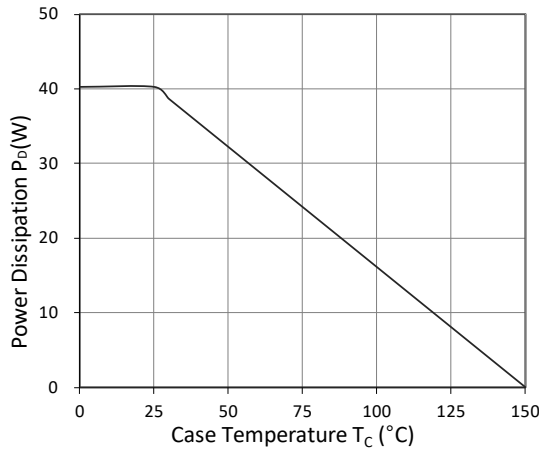


Figure 9. Power Dissipation

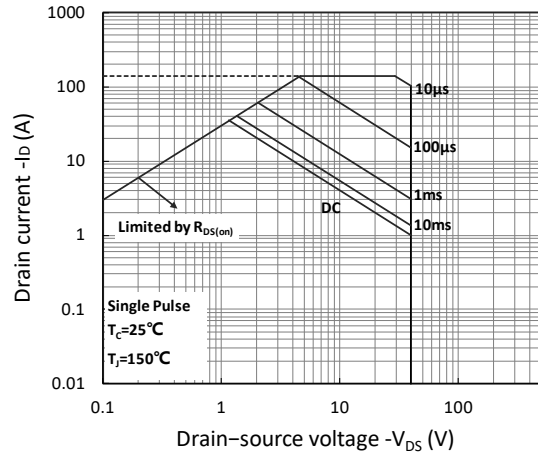


Figure 10. Safe Operating Area

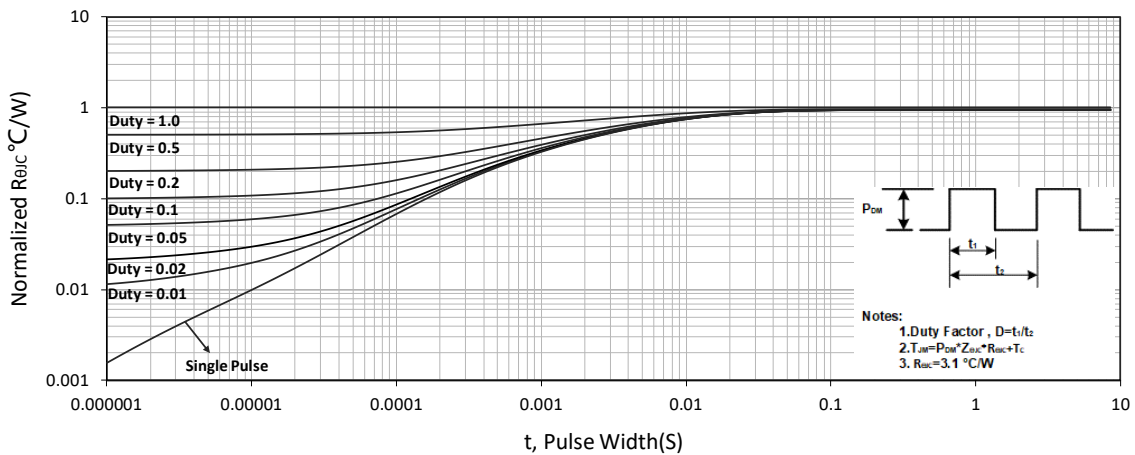


Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuit

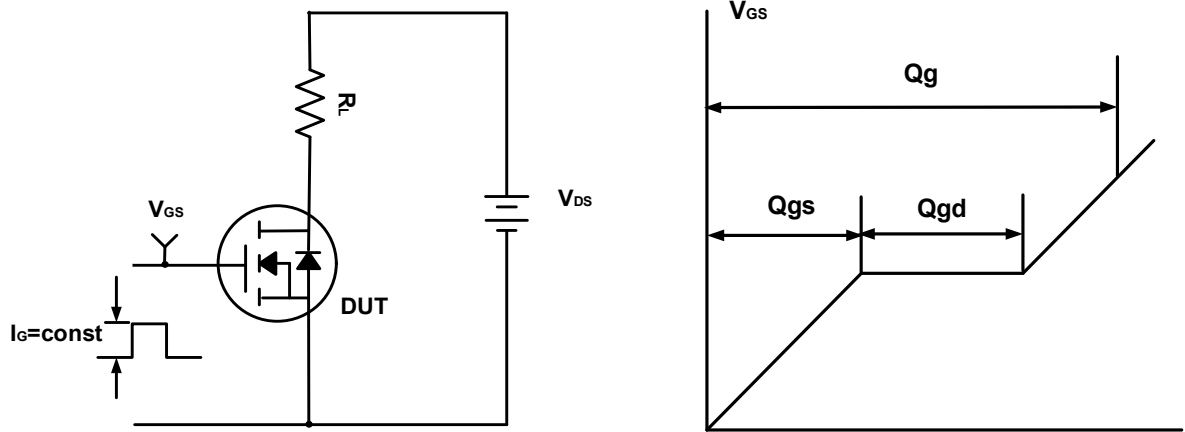


Figure A. Gate Charge Test Circuit & Waveforms

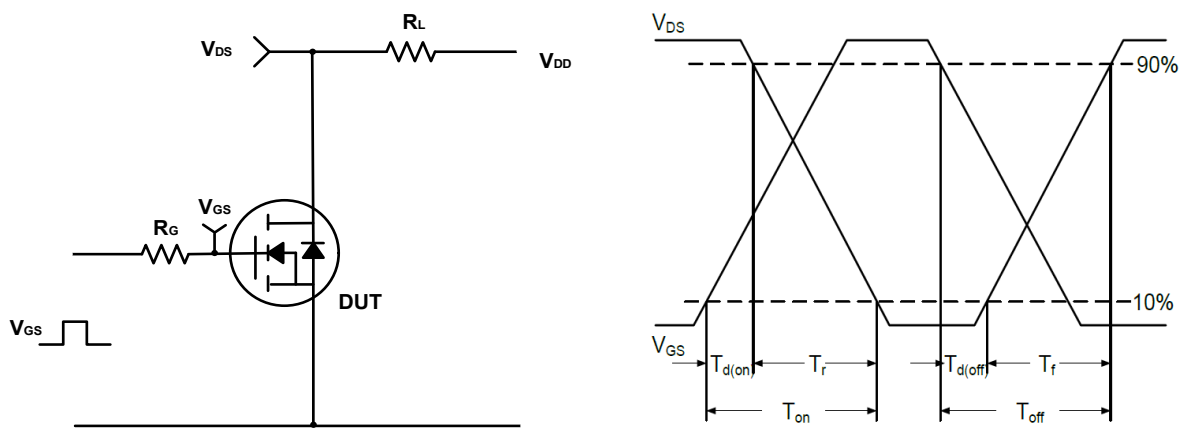


Figure B. Switching Test Circuit & Waveforms

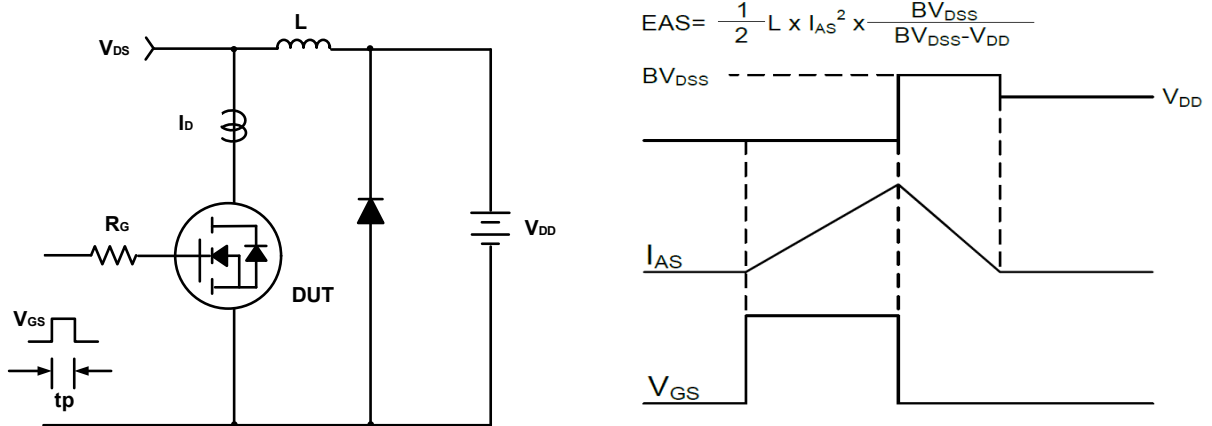
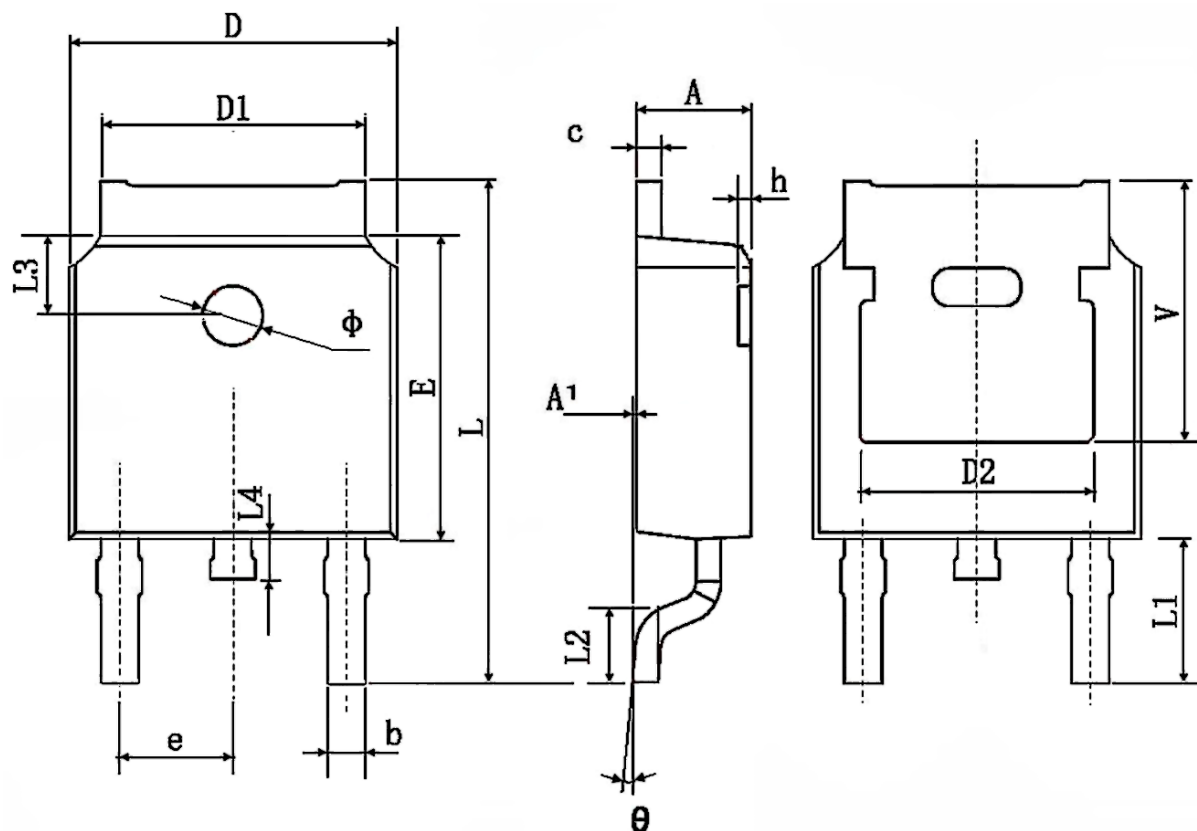


Figure C. Unclamped Inductive Switching Circuit & Waveforms

Package Information

TO252-2L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	

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